

/ Descriptions

TO-92 PNP Silicon PNP transistor in a TO-92 Plastic Package.

/ Features

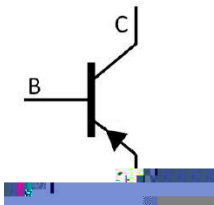
h_{FE} , V_{CEO}

High total power dissipation, high h_{FE} and high V_{CEO} .

/ Applications

Audio frequency amplifier and driver stage.

/ Equivalent Circuit



/ Pinning



PIN1 Base PIN 2 Collector PIN 3 Emitter

/ h_{FE} Classifications & Marking

h_{FE} Classifications Symbol	M	L	K
h_{FE} Range	90~180	135~270	200~400

2SA953

Rev.E Mar.-2016



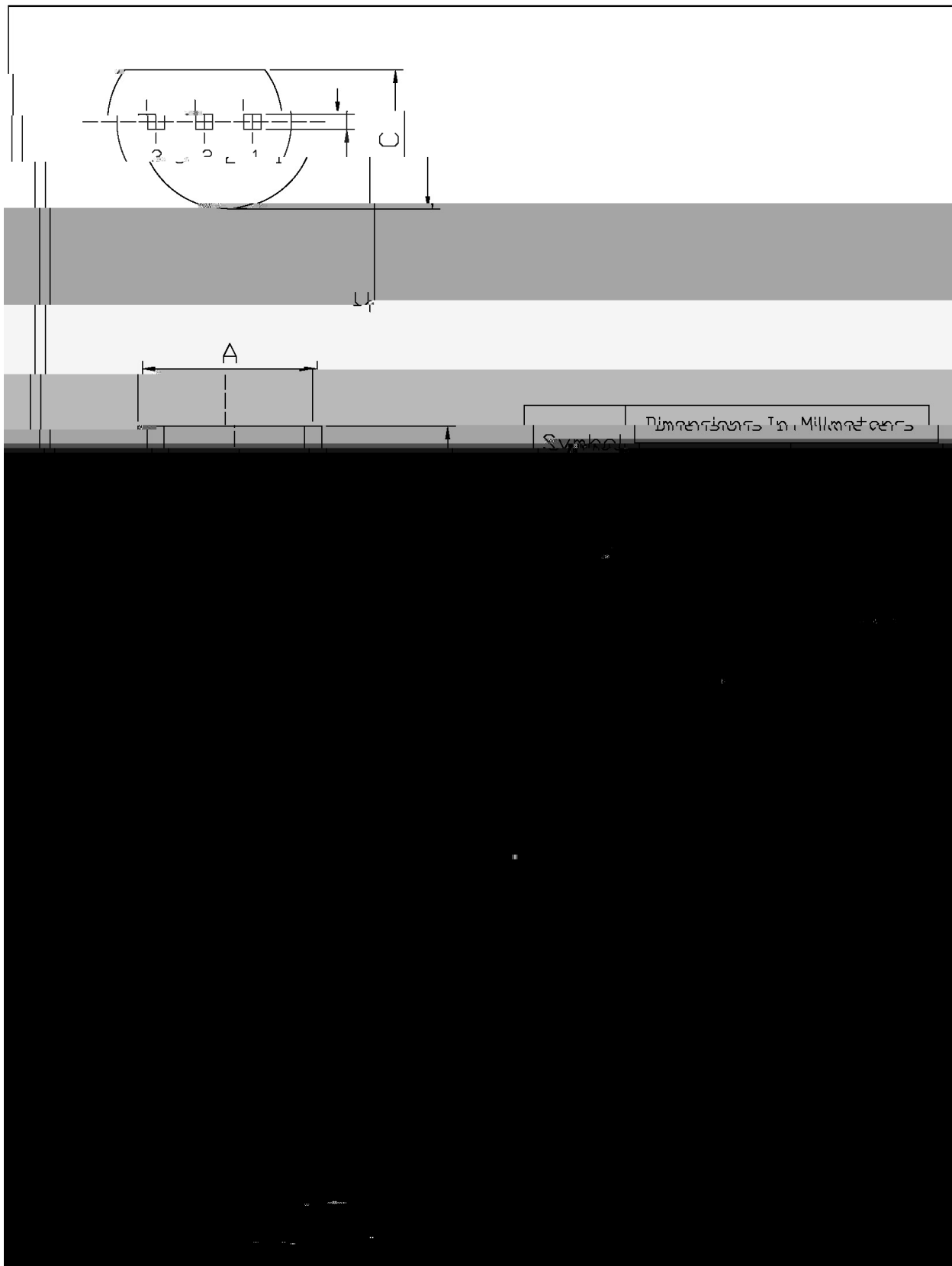
DATA SHEET

Parameter	Symbol	Rating	Unit
Collector to Base Voltage	V_{CBO}	-60	V
Collector to Emitter Voltage	V_{CEO}	-60	V
Emitter to Base Voltage	V_{EBO}	-5.0	V
Collector Current - Continuous	I_C	-300	mA
Base Current – Continuous	I_B	-60	mA
Collector Power Dissipation	P_C	600	mW
Junction Temperature	T_J	150	
Storage Temperature Range	T_{stg}	-55 150	

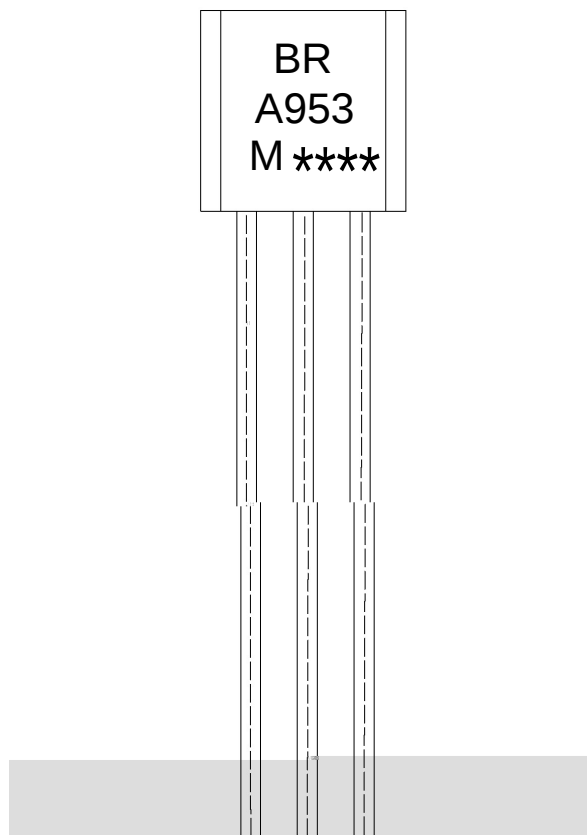
/ Package Dimensions

TO-92

Unit: mm



/ Marking Instructions



BR:

A953

M: h_{FE}

Note:

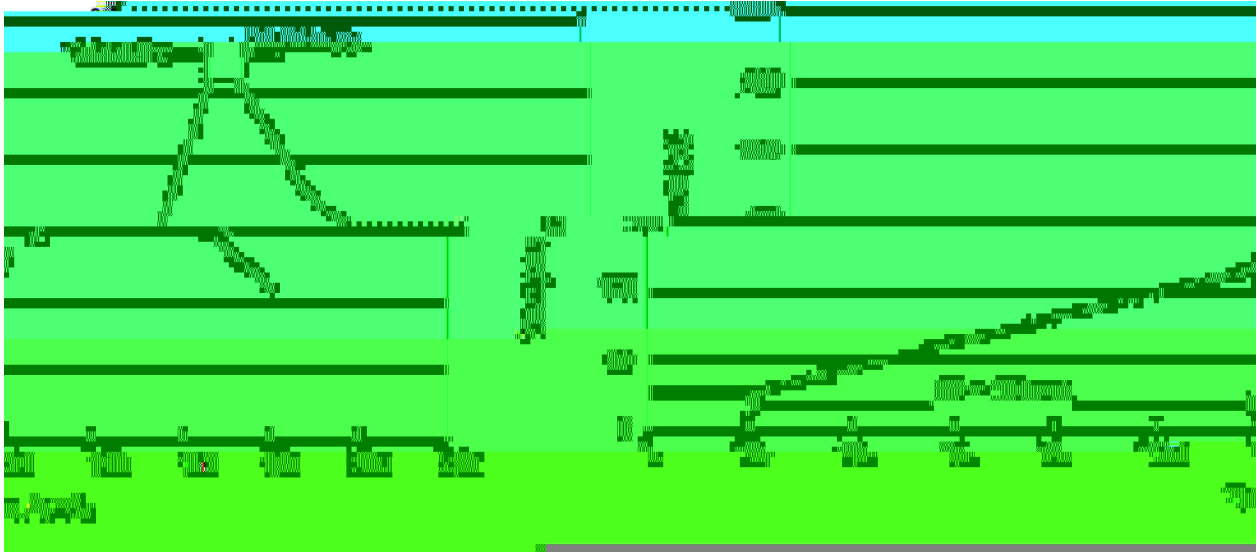
BR: Company Code.

A953: Product Type.

M: h_{FE} Classifications Symbol

****: Lot No. Code, code change with Lot No.

() / Temperature Profile for Dip Soldering(Pb-Free)



Note:

- | | | | | | |
|---|-------|-----|-----------|---|--------------------------------------|
| 1 | 25 | 150 | 60 | 90sec; | 1.Preheating:25~150 , Time:60~90sec. |
| 2 | 255±5 | | 5±0.5sec; | 2.Peak Temp.:255±5 , Duration:5±0.5sec. | |
| 3 | | 2 | 10 /sec. | 3. Cooling Speed: 2~10 /sec. | |

/ Resistance to Soldering Heat Test Conditions

270±5 10±1 sec. Temp:270±5 Time:10±1 sec

/ Packaging SPEC.

/ BULK

Package Type	Units					Dimension (unit mm3)		
	Units/Bag /	Bags/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Bag	Inner Box	Outer Box
TO-92	1,000	10	10,000	5	50,000	135×190	237×172×102	560×245×195
	1,000	10	10,000	10	100,000	135×190	237×172×102	560×245×375

/ AMMO

Package Type	Units	Dimension	(unit mm3)
Units/tape			